



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-06-25
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDRF CHAMPION	Representative title	MDRF Material Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U073KBU6	62MG*489XXXA	A	998Z	2025-06-25
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	51	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	5x5	32	Flat	
Comment	Package : A0B8 UFQFPN 5X5X0.55 32L 0.5 MM PITCH 8202208			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-21st January 2025				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	62MG*489XXXA		51.261		600000	100000
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	3.339	mg	supplier	die	Silicon (Si)	7440-21-3		3.016	mg	903243	58841
				supplier	metallization	Aluminium (Al)	7429-90-5		0.015	mg	4420	288
				supplier	metallization	Copper (Cu)	7440-50-8		0.138	mg	41257	2688
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.044	mg	13261	864
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	491	32
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	491	32
				supplier	Passivation	Silicon Nitride	12033-89-5		0.034	mg	10314	672
				supplier	Passivation	Silicon Oxide	7631-86-9		0.089	mg	26523	1728
				Glue Epoxy (EN4900GC)	Other Organic Materials	0.428	mg	supplier	Organic Compounds	Acrylic resin	Proprietary	
supplier	Organic Compounds	Polybutadiene derivative	Proprietary						0.009	mg	20000	167
supplier	Organic Compounds	Butadiene copolymer	Proprietary						0.006	mg	15000	125
supplier	Organic Compounds	Acrylate	Proprietary						0.023	mg	54000	451
supplier	Organic Compounds	Epoxy resin	Proprietary						0.013	mg	30000	250
supplier	Organic Compounds	Peroxide	Proprietary						0.003	mg	8000	67
supplier	Organic Compounds	Additive	Proprietary						0.008	mg	18000	150
supplier	Metals	Silver	7440-22-4						0.336	mg	785000	6554
Encapsulation (G700LALA)	Other Organic Materials	16.423	mg	supplier	Organic Compounds	Epoxy Resin	Proprietary		0.903	mg	55000	17621
				supplier	Organic Compounds	Phenol Resin	Proprietary		0.345	mg	21000	6728
				supplier	Glass	Silica(Amorphous)A	60676-86-0		13.138	mg	800000	256301
				supplier	Glass	Silica(Amorphous)B	7631-86-9		1.954	mg	119000	38125
				supplier	Organic Compounds	Carbon Black	1333-86-4		0.082	mg	5000	1602
Bonding wire (Cu)	Bonding Wire	0.152	mg	supplier	Metals	Copper	7440-50-8		0.147	mg	965500	2865
				supplier	Metals	Palladium	7440-05-3		0.005	mg	31000	92
				supplier	Metals	Gold	7440-57-5		0.001	mg	3500	10
Plating anode (Sn)	Other inorganic materials	0.719	mg	supplier	Metals	Tin	7440-31-6		0.719	mg	1000000	14025
Leadframe (C7025 + Ag)	Copper & its alloys	30.200	mg	supplier	Metals	Copper	7440-50-8		27.698	mg	917140	540322
				supplier	Metals	Nickel	7440-02-0		0.680	mg	22500	13256
				supplier	Metals	Silicon	7440-21-3		0.079	mg	2600	1532
				supplier	Metals	Magnesium	7439-95-4		0.035	mg	1150	678
				supplier	Metals	Silver	7440-22-4		1.710	mg	56610	33351